ON Semiconductor®

Initial Product/Process Change Notification

Document #:IPCN22948X
Issue Date:31 Oct 2019

Title of Change:	Assembly and Test Transfer of NB3U23CMNTAG from SPEL to SBN with mold compound change.
Proposed First Ship date:	01 May 2020 or earlier if approved by customer
Contact Information:	Contact your local ON Semiconductor Sales Office or Eric.Rupnow@onsemi.com
PCN Samples Contact:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Marking of Parts/ Traceability of Change:	Affected products will be identified with date code code from new plant.
Change Category:	Assembly Change, Test Change
Change Sub-Category(s):	Manufacturing Site Change

Sites Affected:

ON Semiconductor Sites	**External Foundry/Subcon Sites**
ON Semiconductor Seremban, Malaysia	SPEL Semiconductor Limited

Description and Purpose:

Transfer assembly and test from SPEL to SBN which includes change in Leadframe design and mold material.

	Before Change Description	**After Change Description**
LeadFrame	LF PPF Frame (COL design)	LF PPF Frame (COL design)
Die Attach	8006NS	8006NS
Mold Compound	CEL9220ZHF10L	G760
Assembly Site	SPEL	SBN
Test Site	SPEL	SBN

No package dimension change and no product performance change.

Qualification Plan:

QV DEVICE NAME: **NB3U23CMNTAG**
RMS: **S59248**
PACKAGE: **UDFN-6**

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Ta= 125°C, 120% nominal Vcc	504 hrs
TC	JESD22-A104	Ta= -65°C to + 150°C	500 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs
UHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260°C	
SD	JSTD002B	Ta = 245C, 10 sec	

Estimated date for qualification completion: 6 January 2020

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal.***

Part Number	Qualification Vehicle
NB3U23CMNTAG	NB3U23CMNTAG